

IN THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

1-5. (canceled).

6. (currently amended) A method of manufacturing a self- light-emitting device, comprising the steps of:

~~filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and~~

~~discharging said application liquid comprising said an organic light-emitting material to a pixel column over a substrate from a nozzle by ultrasonic oscillations while contacting a contact element attached to the nozzle to a bank so that the nozzle and the pixel column are connected through the application liquid comprising said organic light-emitting material.~~

7. (currently amended) A method of manufacturing a self- light-emitting device according to claim 6, wherein [[:]] said nozzle has a large internal diameter portion and a small internal diameter portion ;~~said small internal diameter portion has a heater; and said heater applies heat to the application liquid filling the nozzle.~~

8-18. (canceled)

19. (currently amended) A method of manufacturing a light-emitting device according to claim 6, ~~wherein said self light-emitting device comprises~~ further comprising forming a pixel electrode over [[a]] ~~the substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.~~

20-25. (canceled)

26. (currently amended) A method of manufacturing a light-emitting device according to claim 6, further comprising:

forming a ~~at least first and second~~ thin film ~~transistors~~ transistor over [[a]] the substrate;

forming an insulating film over ~~said at least first and second~~ thin film ~~transistors~~ ~~transistor~~;

~~forming at least first and second pixel electrodes over said insulating film;~~

~~forming a bank covering at least an edge portion of said first pixel electrode and an edge portion of the second pixel electrode over said insulating film;~~

~~filling a nozzle with an application liquid comprising a light emitting material for forming an EL layer; and~~

~~discharging said application liquid comprising said light emitting material to the first and second pixel electrodes so that the EL layer has a stripe shape over the first and second pixel electrodes by ultrasonic oscillations while the nozzle and the first and second pixel electrodes are connected through the application liquid comprising said light emitting material,~~

~~wherein the first and second pixel electrodes are electrically connected to the first and~~

~~second thin film transistors respectively, and~~

~~wherein the light emitting material comprises an organic material.~~

27-30. (canceled)

31. (currently amended) A method of manufacturing a ~~self~~ light-emitting device according to claim 6, comprising the steps of: wherein

~~filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and~~

~~discharging said application liquid comprising said organic light-emitting material is discharged to a pixel column by ultrasonic oscillations with scanning the nozzle along a direction parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light emitting material.~~

32-47. (canceled).

48. (New) A method of manufacturing a light-emitting device according to claim 6, wherein ultrasonic oscillation is applied to the liquid comprising the organic light-emitting material when the liquid is discharged from the nozzle.

49. (New) A method of manufacturing a light-emitting device according to claim 6, wherein the liquid comprising the organic light-emitting material is heated when the liquid is

discharged from the nozzle.

50. (New) A method manufacturing a light-emitting device according to claim 6, wherein the bank comprises a resin material.

51. (New) A method manufacturing a light-emitting device according to claim 19, wherein the bank covers an edge portion of the pixel electrode.